

AMENDMENTS TO THE ABSTRACT:

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Please replace the original abstract with the following rewritten abstract:

ABSTRACT OF THE DISCLOSURE

FI --A process for sawing a substrate strip marks corresponding to substrate areas of substrate strips which are arranged side-by-side on a plate. A saw machine is mechanically moved to the substrate areas and positioned by the alignment marks of corresponding substrate areas for cutting the substrate areas of the substrate strips in the first phase. Then the saw machine is further mechanically moved to the substrate areas again and is positioned by the alignment marks of corresponding substrate areas again for cutting the substrate areas of the substrate strips in the second phase. Therefore, an error in any of the substrate areas in the first phase and second phase will not accumulate to the subsequent substrate areas in the substrate strip.--
